

CCD area image sensors

S8980

S10810-11

Front-illuminated FFT-CCDs for X-ray imaging

The S8980 is an FFT-CCD image sensor suitable for intra-oral X-ray imaging in dental diagnosis. The S8980 has 1.5 mega (1500×1000) pixels, each of which is $20 \times 20 \, \mu m$ in size. The FOP (fiber optic plate) used as an input window is as thin as 1.5 mm, making high resolution as well as highly resistant to X-ray irradiation. The scintillator coated on the FOP is optimized to have high X-ray sensitivity and high resolution ($20 \, \text{Lp/mm}$).

The S10810-11 is an easy-to-use X-ray imaging module using the S8980, with added functions such as a cable assembly and X-ray trigger circuit.

Features

- X-ray monitoring photodiode incorporated
- Compact size
- High dynamic range: 12-bit
- **■** Long-term stability
- Resolution: 20 Lp/mm
- **1500 (H)** × **1000 (V)** pixel format
- Pixel size: 20 × 20 μm
- Coupled with FOS for X-ray imaging
- **100% fill factor**
- Low dark signal
- Low readout noise
- MPP operation
- AC/DC X-ray source adapted

Applications

- Intra-oral X-ray imaging in dental diagnosis
- General X-ray imaging
- Non-destructive inspection

These products are components for incorporation into medical device.

Structure

Parameter	S8980	S10810-11	
CCD structure	Full frame transfer		
Fill factor	100	0%	
Cooling	Non-c	cooled	
Number of pixels	1508 (H) >	× 1002 (V)	
Number of active pixels	1500 (H) × 1000 (V)		
Pixel size	20 (H) × 20 (V) μm		
Active area	30 (H) × 2	20 (V) mm	
Vertical clock phase	2 ph	ases	
Horizontal clock phase	2 phases		
Output circuit	Emitter follower without load resistance		
Dimensions	35.5 (H) × 23.2 (V) mm 41.0 (H) × 26.4 (V) mm		
Window	FOS (scintillator on 1.5 mm FOP)		

→ Absolute maximum ratings (Ta=25 °C)

Parameter	Symbol	Min.	Тур.	Max.	Unit
Storage temperature	Tstg	-20	-	+70	°C
Operating temperature	Topr	0	-	+40	°C
Total dose irradiation	D	-	-	50	Gy
OD voltage	Vod	-0.5	-	+20	V
RD voltage	Vrd	-0.5	-	+18	V
SG voltage	Vsg	-15	-	+15	V
OG voltage	Vog	-15	-	+15	V
RG voltage	VRG	-15	-	+15	V
TG voltage	VTG	-15	-	+15	V
Vertical clock voltage	VP1V, VP2V	-15	-	+15	V
Horizontal clock voltage	VP1H, VP2H	-15	-	+15	V
Vcc voltage	Vcc	0	-	+7	V

□ Operating conditions (MPP mode, Ta=25 °C)

Parameter		Symbol	Min.	Тур.	Max.	Unit
Output transistor drain voltage	Output transistor drain voltage		12	15	-	V
Reset drain voltage		Vrd	12	13	14	V
Output gate voltage		Vog	-0.5	2	5	V
Substrate voltage		Vss	-	0	-	V
Vertical shift register	High	VP1VH, VP2VH	0	3	6	V
clock voltage	Low	VP1VL, VP2VL	-9	-8	-7	V
Horizontal shift register	High	VP1HH, VP2HH	0	3	6	V
clock voltage	Low	VP1HL, VP2HL	-9	-8	-7	V
Summing gate voltage	High	VsGH	0	3	6	V
Summing gate voltage	Low	VsGL	-9	-8	-7	V
Reset gate voltage	High	Vrgh	0	3	6	V
Reset gate voltage	Low	VRGL	-9	-8	-7	V
Transfer gate voltage	High	VTGH	0	3	6	V
Transfer gate voltage	Low	VTGL	-9	-8	-7	V
+5 V power supply voltage	-	Vcc	4.75	5	5.25	V

➡ Electrical characteristics (Ta=25 °C)

Parameter	Parameter		Min.	Тур.	Max.	Unit
Signal output frequency*1	gnal output frequency*1		-	1	-	MHz
Vertical shift register capacita	ance	CP1V, CP2V	-	60000	-	pF
Horizontal shift register	S8980	Ср1н, Ср2н	-	350	-	pF
capacitance	S10810-11	CPIH, CPZH	-	550	-	þΓ
Summing gate canacitance	S8980	CsG	-	20	-	nE
Summing gate capacitance	S10810-11	CSG	-	220	-	pF
Reset gate capacitance	S8980	Crg -	-	20	-	pF
Reset gate capacitance	S10810-11		-	220	-	
Transfer gate capacitance	S8980	Стд	-	250	-	nE
Transfer gate capacitance	S10810-11	CIG	-	450	-	pF
Charge transfer efficiency*2		CTE	0.99995	0.99998	-	-
DC output level*3	DC output level*3		5	8	11	V
Output impedance*3		Zo	-	500	-	Ω
Power dissipation*3 *4		Р	-	75	-	mW
LEV power supply surrent	S8980 -	-	1	-	mΛ	
+5 V power supply current	S10810-11	Icc	-	2	-	mA mA

^{*1:} In case of the S8980, maximum frequency strongly depends on a peripheral circuit and cable length.



^{*2:} Measured at half of the full well capacity. CTE is defined per pixel.
*3: Vop=15 V

^{*4:} Power dissipation of the on-chip amplifier

Electrical and optical characteristics (Ta=25 °C, VoD=15 V, unless otherwise noted)

	Parameter		Symbol	Min.	Тур.	Max.	Unit		
		Vertical		100	200	-			
Full well capa	city	Horizontal	Fw	-	300	-	ke⁻		
		Summing		-	600	-			
CCD node ser	nsitivity* ⁵		Sv	1.0	1.4	-	μV/e ⁻		
Dark current	Dark current (MPP mode)*6				DS	-	250	2500	e /pixel/s
Readout noise	Readout noise*7		Nr	-	60	-	e⁻rms		
Dynamic rang	Dynamic range*8		DR	-	3333	-	-		
X-ray respons	e non-uniformi	ty* ⁹ * ¹⁰	XRNU	-	±10	±30	%		
	Point	White spots		-	=	20			
Blemish*11	defects*12	Black spots		-	-	20			
Cluster defects*13 Column defects*14		<u>-</u>	-	-	3	_			
		ts*14		-	-	1			
X-ray resolution	on* ⁹		ΔR	15	20	-	Lp/mm		

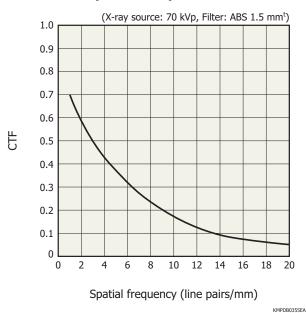
^{*5:} VoD=15 V, RL (load resistance of emitter follower)=1 $k\Omega$

Noise: Fixed pattern noise (peak to peak)

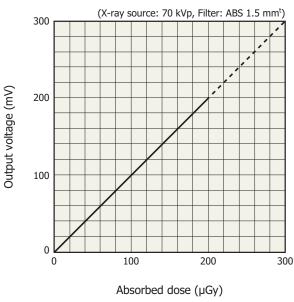
In the range that excludes 5 pixels from edges to the center at every position

Black spots > 50% reduction in response relative to adjacent pixels, measured at half of the full well capacity

Resolution (S10810-11)



- Response (S10810-11)



KMPDB0356EA

^{*6:} Dark signal doubles for every 5 to 7 °C.

^{*7: -40 °}C, operating frequency is 1 MHz.

^{*8:} Dynamic range = Full well capacity / Readout noise

^{*9:} X-ray irradiation of 60 kVp, measured at half of the full well capacity

^{*10:} XRNU (%) = Noise / Signal × 100

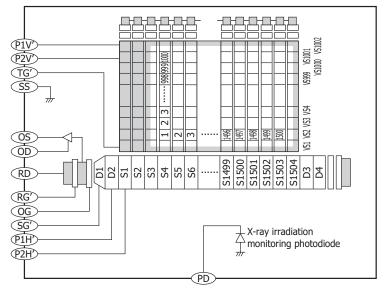
^{*11:} Refer to "Characteristics and use of FFT-CCD area image sensor" of technical information.

^{*12:} White spots > 10 times of Max. Dark signal (2500 e⁻/pixel/s)

^{*13:} Continuous 2 to 9 point defects

^{*14:} Continuous ≥ 10 point defects

Device structure



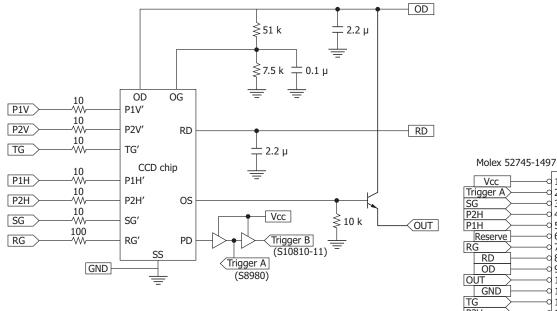
KMPDC0163EA

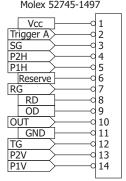
Pixel format

	Left ← Horizontal direction → Right					
Blank	Optical black	Isolation	Effective	Isolation	Optical black	Blank
2	2	1	1500	1	0	2

Top ← Vertical direction → Bottom					
Isolation Effective Isolation					
1	1				

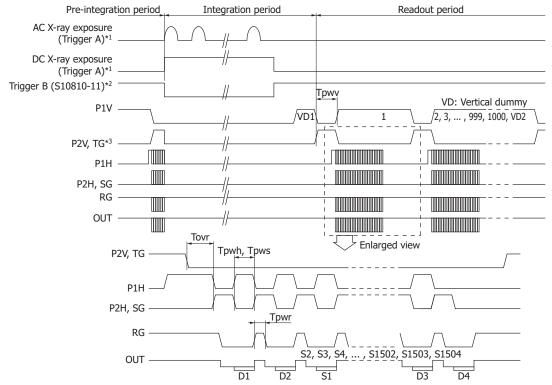
- On-board circuit





KMPDC0348EB

- Timing chart



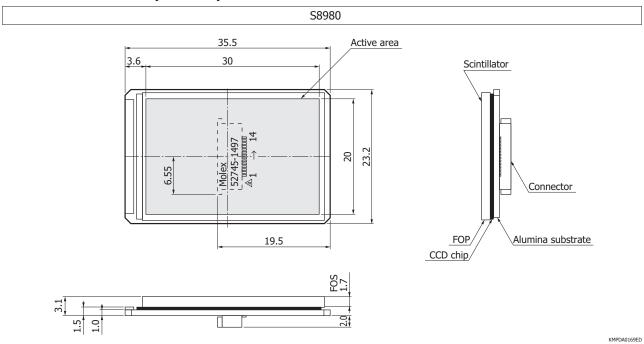
- *1: Trigger A (S8980) is the same as AC/DC X-ray exposure form.
- *2: Low active trigger pulse
- *3: TG terminal can be short-circuited to P2V terminal.

KMPDC0349EB

Para	Symbol	Min.	Typ.	Max.	Unit	
D1V D2V TC	Pulse width*15	tpwv	30	60	-	μs
P1V, P2V, TG	Rise and fall times	tprv, tpfv	200	-	-	ns
	Pulse width	tpwh	100	500	-	ns
P1H, P2H	Rise and fall times*15	tprh, tpfh	5	-	-	ns
	Duty ratio	-	-	50	-	%
	Pulse width	tpws	100	500	-	ns
SG	Rise and fall times	tprs, tpfs	3	-	-	ns
	Duty ratio	-	-	50	-	%
RG	Pulse width	tpwr	10	50	-	ns
	Rise and fall times	tprr, tpfr	3	-	-	ns
TG-P1H	Overlap time	tovr	18	36	-	μs

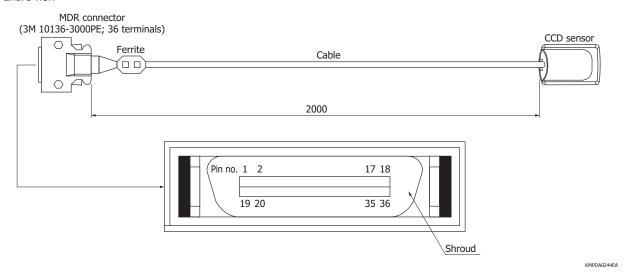
^{*15:} The clock pulses should be overlapped at 50% of maximum amplitude.

Dimensional outlines (unit: mm)

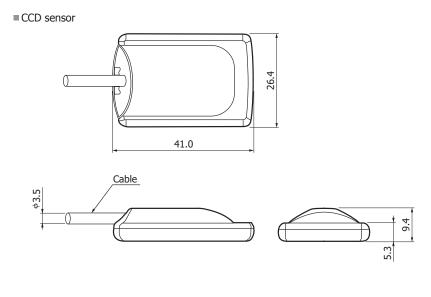


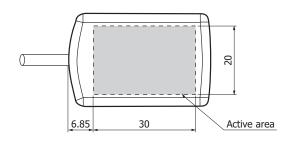
S10810-11

■ Entire view



* The shield of cable and the shroud of MDR connector are short-circuited. Take due care of EMC and ESD when connected to 0 V reference and the ground.





KMPDA0245EB

₽ Pin connections

	S8980					
Pin no.	Symbol	Description	Remark			
1	Vcc	Analog power +5 V				
2	Trigger A	Trigger A output				
3	SG	Summing gate				
4	P2H	CCD horizontal register clock-2				
5	P1H	CCD horizontal register clock-1				
6	Reserve		Should be opened			
7	RG	Reset gate				
8	RD	Reset drain				
9	OD	Output transistor drain				
10	OUT	Signal output				
11	GND	Ground				
12	TG	Transfer gate				
13	P2V	CCD vertical register clock-2				
14	P1V	CCD vertical register clock-1				

CCD area image sensors

S8980, S10810-11

S10810-11

Pin no.	Symbol	Description	Remark
1	GND	Ground	
2	Vcc	+5 V power supply	
3	SG	Summing gate	Same timing as P2H
4	Trigger B	Trigger B output	
5	RG	Reset gate	
6	NC		
7	Reserve		Should be opened
8	NC		
9	RD	Reset drain	
10	NC		
11	OD	Output transistor drain	
12	NC		
13	OUT	Sensor output	
14	NC		
15	GND	Ground	
16	NC		
17	P1V	CCD vertical register clock-1	
18	Reserve		Should be opened
19	Reserve		Should be opened
20	P2H	CCD horizontal register clock-2	
21	NC		
22	P1H	CCD horizontal register clock-1	
23	NC		
24	GND	Ground	
25	NC		
26	RD	Reset drain	
27	NC		
28	OD	Output transistor drain	
29	NC		
30	GND	Ground	
31	NC		
32	OUT	Sensor output	
33	NC		
34	P2V	CCD vertical register clock-2	
35	NC		
36	TG	Transfer gate	Same timing as P2V



S8980, S10810-11

Precautions

- Electrostatic countermeasures
- · Handle these sensors with bare hands or wearing cotton gloves. In addition, wear anti-static clothing or use a wrist band with an earth ring, in order to prevent electrostatic damage due to electrical charges from friction.
- · Avoid directly placing these sensors on a work-desk or work-bench that may carry an electrostatic charge.
- · Provide ground lines or ground connection with the work-floor, work-desk and work-bench to allow static electricity to discharge.
- · Ground the tools used to handle these sensors, such as tweezers and soldering irons.

It is not always necessary to provide all the electrostatic measures stated above. Implement these measures according to the amount of damage that occurs.

Information described in this material is current as of May, 2011. Product specifications are subject to change without prior notice due to improvements or other reasons. Before assembly into final products, please contact us for the delivery specification sheet to check the latest information.

Type numbers of products listed in the delivery specification sheets or supplied as samples may have a suffix "(X)" which means preliminary specifications or a suffix "(Z)" which means developmental specifications.

The product warranty is valid for one year after delivery and is limited to product repair or replacement for defects discovered and reported to us within that one year period. However, even if within the warranty period we accept absolutely no liability for any loss caused by natural disasters or improper product use.

 $Copying \ or \ reprinting \ the \ contents \ described \ in \ this \ material \ in \ whole \ or \ in \ part \ is \ prohibited \ without \ our \ prior \ permission.$

HAMAMATSU

www.hamamatsu.com

HAMAMATSU PHOTONICS K.K., Solid State Division

1126-1 Ichino-cho, Higashi-ku, Hamamatsu City, 435-8558 Japan, Telephone: (81) 53-434-3311, Fax: (81) 53-434-5184

U.S.A.: Hamamatsu Corporation: 360 Foothill Road, P.O.Box 6910, Bridgewater, N.J. 0880-70910, U.S.A., Telephone: (1) 908-231-0960, Fax: (1) 908-231-1218

Germany: Hamamatsu Photonics Deutschland GmbH: Arzbergerst: 10, D-82211 Herrsching am Ammersee, Germany, Telephone: (49) 8152-375-0, Fax: (49) 8152-265-8

France: Hamamatsu Photonics France S.A.R.L.: 19, Rue du Saule Trapu, Parc du Moulin de Massy, 91882 Massy Cedex, France, Telephone: 33-(1) 69 53 71 00, Fax: 33-(1) 69 53 71 10

United Kingdom: Hamamatsu Photonics Urt. Britisted: 2 Howard Court, 10 Tewin Road, Welvyn Garden City, Hertfordsthire AL7 IBW, United Kingdom, Telephone: (44) 1707-325777

North Europe: Hamamatsu Photonics Norden AB: Smidesvägen 12, 56-171 41 Solna, Sweden, Telephone: (46) 8-509-031-00, Fax: (46) 8-509-031-01

Italy: Hamamatsu Photonics Italia S.R.L.: Strada della Moia, 1 int. 6, 20020 Arese, (Milano), Italy, Telephone: (39) 02-935-81-733, Fax: (39) 02-935-81-741